

# DAP222, DAP202U

Preferred Device

## Common Anode Silicon Dual Switching Diodes

These Common Anode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. The DAP222 device is housed in the SC-75/SOT-416 package which is designed for low power surface mount applications, where board space is at a premium. The DAP202U device is housed in the SC-70/SOT-323 package.

### Features

- Fast  $t_{rr}$
- Low  $C_D$
- Pb-Free Packages are Available

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	80	Vdc
Peak Reverse Voltage	$V_{RM}$	80	Vdc
Forward Current	$I_F$	100	mAdc
Peak Forward Current	$I_{FM}$	300	mAdc
Peak Forward Surge Current	$I_{FSM}(1)$	2.0	Adc

### THERMAL CHARACTERISTICS

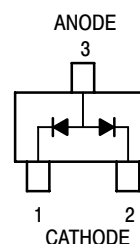
Rating	Symbol	Max	Unit
Power Dissipation	$P_D$	150	mW
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 ~ +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

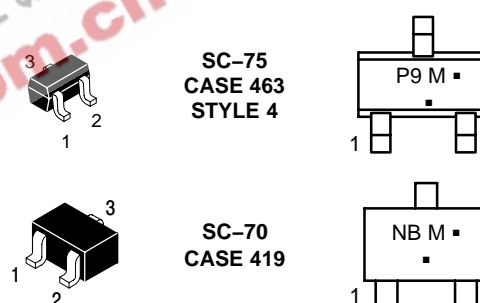


ON Semiconductor®

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### MARKING DIAGRAMS



P9, NB = Device Codes  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
DAP222	SC-75	3000 / Tape & Reel
DAP222G	SC-75 (Pb-Free)	3000 / Tape & Reel
DAP202U	SC-70	3000 / Tape & Reel
DAP202UG	SC-70 (Pb-Free)	3000 / Tape & Reel
DAP222T1	SC-75	3000 / Tape & Reel
DAP222T1G	SC-75 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

# DAP222, DAP202U

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	$I_R$	$V_R = 70\text{ V}$	–	0.1	$\mu\text{A}$
Forward Voltage	$V_F$	$I_F = 100\text{ mA}$	–	1.2	Vdc
Reverse Breakdown Voltage	$V_R$	$I_R = 100\ \mu\text{A}$	80	–	Vdc
Diode Capacitance	$C_D$	$V_R = 6.0\text{ V}, f = 1.0\text{ MHz}$	–	3.5	pF
Reverse Recovery Time	DAP222 $t_{rr}(2)$	$I_F = 5.0\text{ mA}, V_R = 6.0\text{ V}, R_L = 100\ \Omega, I_{rr} = 0.1 I_R$	–	4.0	ns
	DAP202U $t_{tr}(3)$		–	10.0	

- $t = 1\ \mu\text{s}$
- $t_{rr}$  Test Circuit for DAP222 in Figure 4.
- $t_{tr}$  Test Circuit for DAP202U in Figure 5.

## TYPICAL ELECTRICAL CHARACTERISTICS

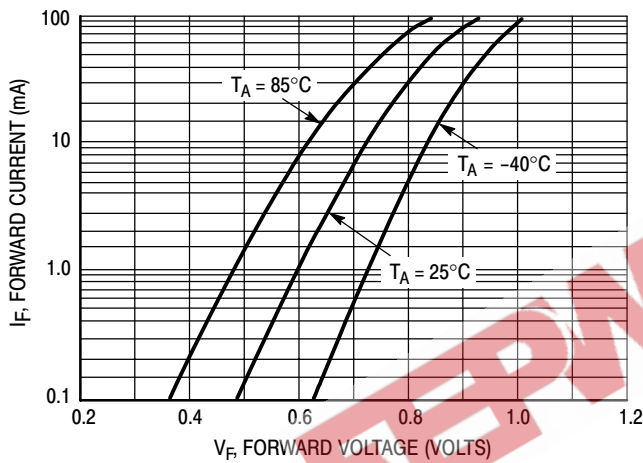


Figure 1. Forward Voltage

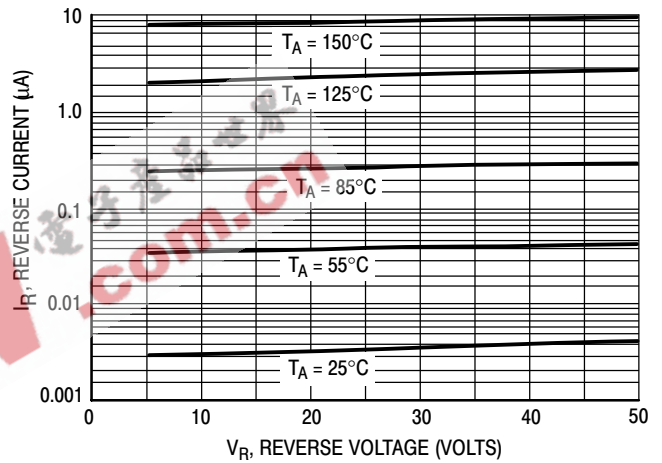


Figure 2. Reverse Current

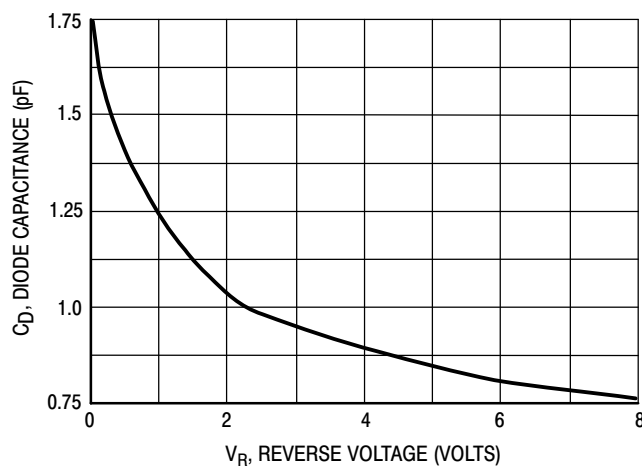


Figure 3. Diode Capacitance

## DAP222, DAP202U

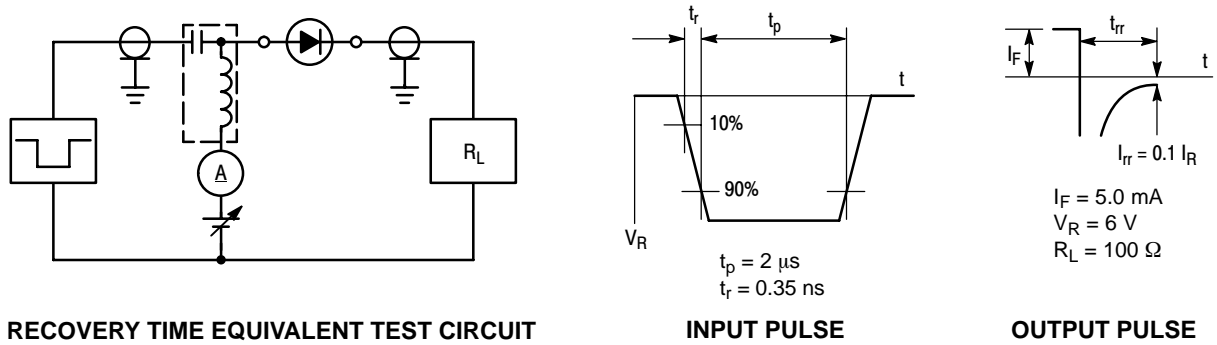


Figure 4. Reverse Recovery Time Test Circuit for the DAP222

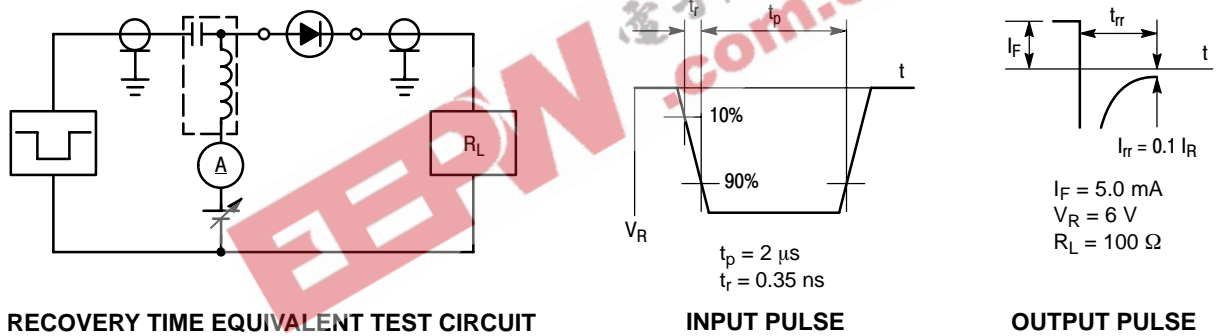


Figure 5. Reverse Recovery Time Test Circuit for the DAP202U

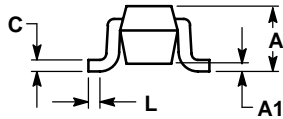
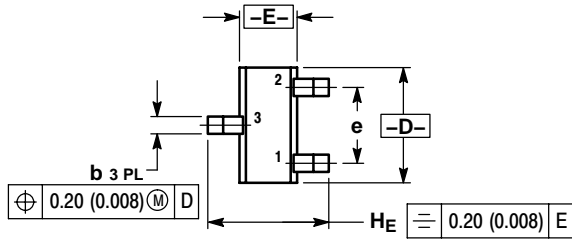
# DAP222, DAP202U

## PACKAGE DIMENSIONS

### SC-75 (SOT-416)

CASE 463-01

ISSUE F



**NOTES:**

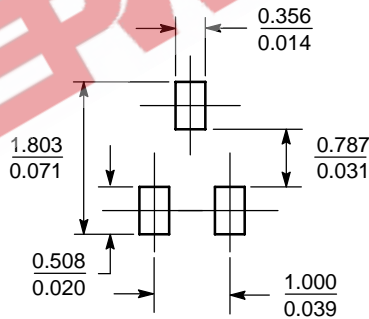
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
C	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.059	0.063	0.067
E	0.70	0.80	0.90	0.027	0.031	0.035
e	1.00 BSC			0.04 BSC		
L	0.10	0.15	0.20	0.004	0.006	0.008
H <sub>E</sub>	1.50	1.60	1.70	0.061	0.063	0.065

**STYLE 4:**

- PIN 1. CATHODE
- CATHODE
- ANODE

### SOLDERING FOOTPRINT\*



SCALE 10:1  $\left( \frac{\text{mm}}{\text{inches}} \right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

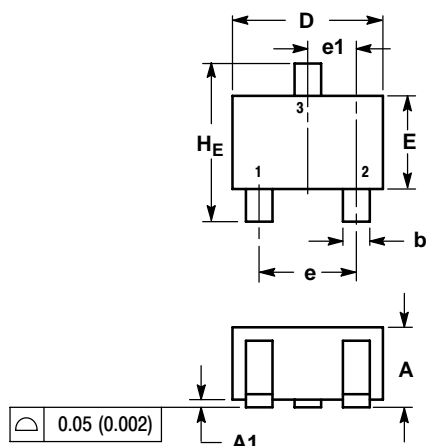
# DAP222, DAP202U

## PACKAGE DIMENSIONS

### SC-70 (SOT-323)

CASE 419-04

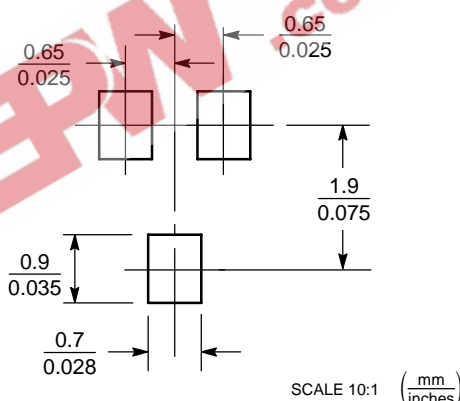
ISSUE M



- NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
HE	2.00	2.10	2.40	0.079	0.083	0.095

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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